

Hesse & Knipps Introduces High-Speed Heavy Wire Bonder



Hesse & Knipps, Inc.

Wire bonder in operation.

Ultra High Performance Clock Osc. from Crystek

Fort Myers, FL — Crystek Corporation has launched the CCHD-957, a new ultra-low phase noise HCMOS clock oscillator with standby mode, with an extremely low close-in phase noise of -100dBc/Hz at 10Hz offset and a typical noise floor of -170dBc/Hz at 100kHz offset. This performance makes the oscillator family an excellent choice for use in applications such as: DACs (digital-to-analog converters), ADCs (analog-to-digital converters), DAB (digital audio broadcasting), and professional CD audio equipment.



SMT crystal clock oscillator.

The oscillator also has a "Standby Function" — when placed in disable mode, the internal oscillator is completely shut down and its output buffer is placed in Tri-State. This oscillator family is housed in a 9 x 14mm SMT package and operates with a +3.3V power supply consuming 16mA of current. Stability is rated at 20 to 50ppm (0 to +70°C) and ±25-50ppm (-40 to +85°C).

The CCHD-957 generates frequencies between 10MHz and 50MHz. Its output driver is capable of driving ±24mA, translating to a rise/fall time of ~3nsec Max at 20 percent to 80 percent Vcc with a 15pF load.

Contact: Crystek Corporation, 12730 Commonwealth Drive, Ft. Myers, FL 33913 ☎ 800-237-3061 or 239-561-3311 fax: 239-561-1025 E-mail: sales@crystek.com Web: www.crystek.com

Paderborn, Germany — Hesse & Knipps, Inc. has unveiled its next generation BONDJET BJ939 Heavy Wire Bonder. The new unit incorporates a heavy wire bond head with integrated pull test and large table travel (305 x 410mm) that meets automotive electronics and power semiconductor requirements.

According to the company, the new bonders provide the large current carrying capacity and high reliability that power electronics manufacturers require. They are also reportedly the fastest heavy wire

bonders available today.

The BONDJET BJ939 handles aluminum, gold and copper heavy round wire and ribbon wire at speeds of 3 wires/sec. Patented PiQC Process Integrated Quality Control analyzes 5 critical measurements of bond quality in real time for every bond, ensuring that only reliable, high quality devices are produced.

The company's automatic wedge bonders handle both light and heavy wire applications with aluminum and gold round wire from 12.5µ to 500µ in diameter, in addi-

tion to ribbon wire from 6 x 35µ up to 0.3 x 2mm, including HCR™ (High Current Ribbon). The product line also includes dispensers, ultrasonic flip chip bonders, standard or customized indexers with or without handling systems, manufacturing process monitoring systems for interfacing with the company's equipment and commercial software packages.

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